

**E15C7J2F-125.000M TR****ITEM DESCRIPTION**

Quartz Crystal Clock Oscillators XO (SPXO) LVPECL (PECL) 2.5Vdc 6 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 125.000MHz  $\pm 25$ ppm over -40°C to +85°C

**ELECTRICAL SPECIFICATIONS**

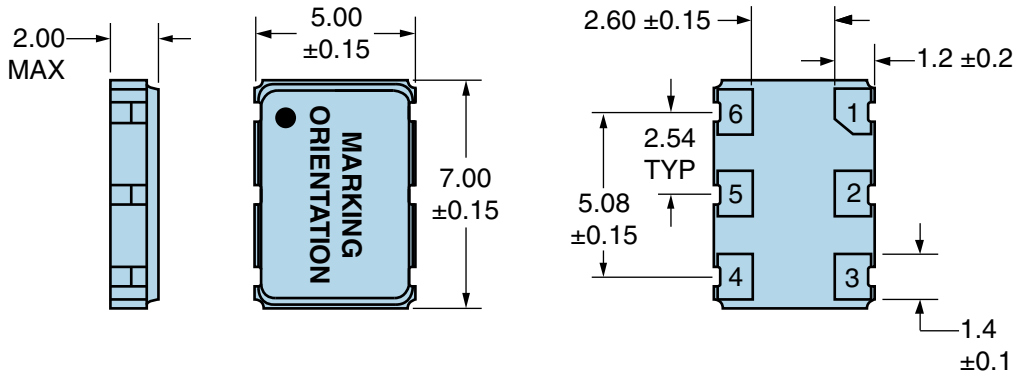
<b>Nominal Frequency</b>	125.000MHz
<b>Frequency Tolerance/Stability</b>	$\pm 25$ ppm Maximum over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance (at 25°C), Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
<b>Supply Voltage</b>	2.5Vdc $\pm 5\%$
<b>Input Current</b>	75mA Maximum
<b>Output Voltage Logic High (Voh)</b>	Vdd-1.085Vdc Minimum, 1.55Vdc Typical, Vdd-0.88Vdc Maximum
<b>Output Voltage Logic Low (Vol)</b>	Vdd-1.83Vdc Minimum, 0.80Vdc Typical, Vdd-1.555Vdc Maximum
<b>Rise/Fall Time</b>	300pSec Typical, 700pSec Maximum (Measured at 20% to 80% of Waveform)
<b>Duty Cycle</b>	50 $\pm 5$ (%) (Measured at 50% of Waveform)
<b>Load Drive Capability</b>	50 Ohms into Vdd-2.0Vdc
<b>Output Logic Type</b>	LVPECL
<b>Phase Noise</b>	-60dBc/Hz at 10Hz Offset, -95dBc/Hz at 100Hz Offset, -125dBc/Hz at 1kHz Offset, -143dBc/Hz at 10kHz Offset, -145dBc/Hz at 100kHz Offset, -145dBc/Hz at 1MHz Offset, -146dBc/Hz at 10MHz Offset (All Values are Typical)
<b>Logic Control / Additional Output</b>	Tri-State and Complementary Output
<b>Tri-State Input Voltage (Vih and Vil)</b>	Vih of 70% of Vdd Minimum or No Connect to Enable Output and Complementary Output, Vil of 30% of Vdd Maximum to Disable High Impedance Output and Complementary Output
<b>Standby Current</b>	30 $\mu$ A Maximum (Without Load)
<b>RMS Phase Jitter</b>	0.4pSec Typical, 1pSec Maximum (Fj=12kHz to 20MHz; Random)
<b>Start Up Time</b>	10mSec Maximum
<b>Storage Temperature Range</b>	-55°C to +125°C

**ENVIRONMENTAL & MECHANICAL SPECIFICATIONS**

<b>ESD Susceptibility</b>	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
<b>Fine Leak Test</b>	MIL-STD-883, Method 1014, Condition A
<b>Flammability</b>	UL94-V0
<b>Gross Leak Test</b>	MIL-STD-883, Method 1014, Condition C
<b>Mechanical Shock</b>	MIL-STD-883, Method 2002, Condition B
<b>Moisture Resistance</b>	MIL-STD-883, Method 1004
<b>Moisture Sensitivity</b>	J-STD-020, MSL 1
<b>Resistance to Soldering Heat</b>	MIL-STD-202, Method 210, Condition K
<b>Resistance to Solvents</b>	MIL-STD-202, Method 215
<b>Solderability</b>	MIL-STD-883, Method 2003
<b>Temperature Cycling</b>	MIL-STD-883, Method 1010, Condition B
<b>Vibration</b>	MIL-STD-883, Method 2007, Condition A

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## MECHANICAL DIMENSIONS (all dimensions in millimeters)

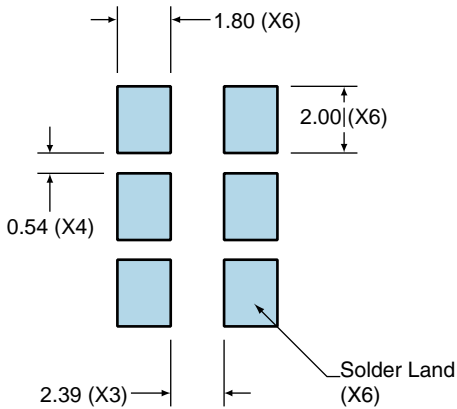


PIN	CONNECTION
1	Tri-State
2	No Connect
3	Case Ground
4	Output
5	Complementary Output
6	Supply Voltage

LINE	MARKING
1	<b>ECLIPTEK</b>
2	<b>125.00M</b>
3	<b>XXXXX</b> XXXXX=Ecliptek Manufacturing Identifier

## Suggested Solder Pad Layout

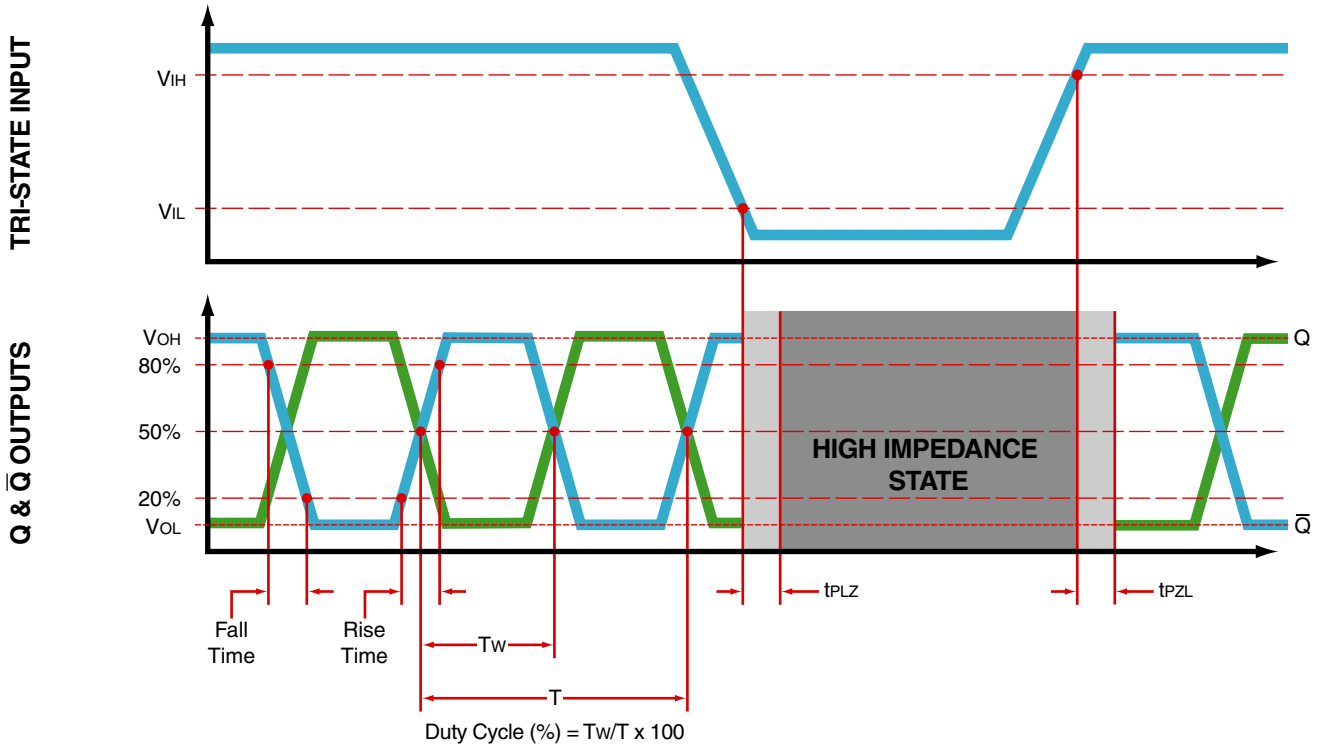
All Dimensions in Millimeters

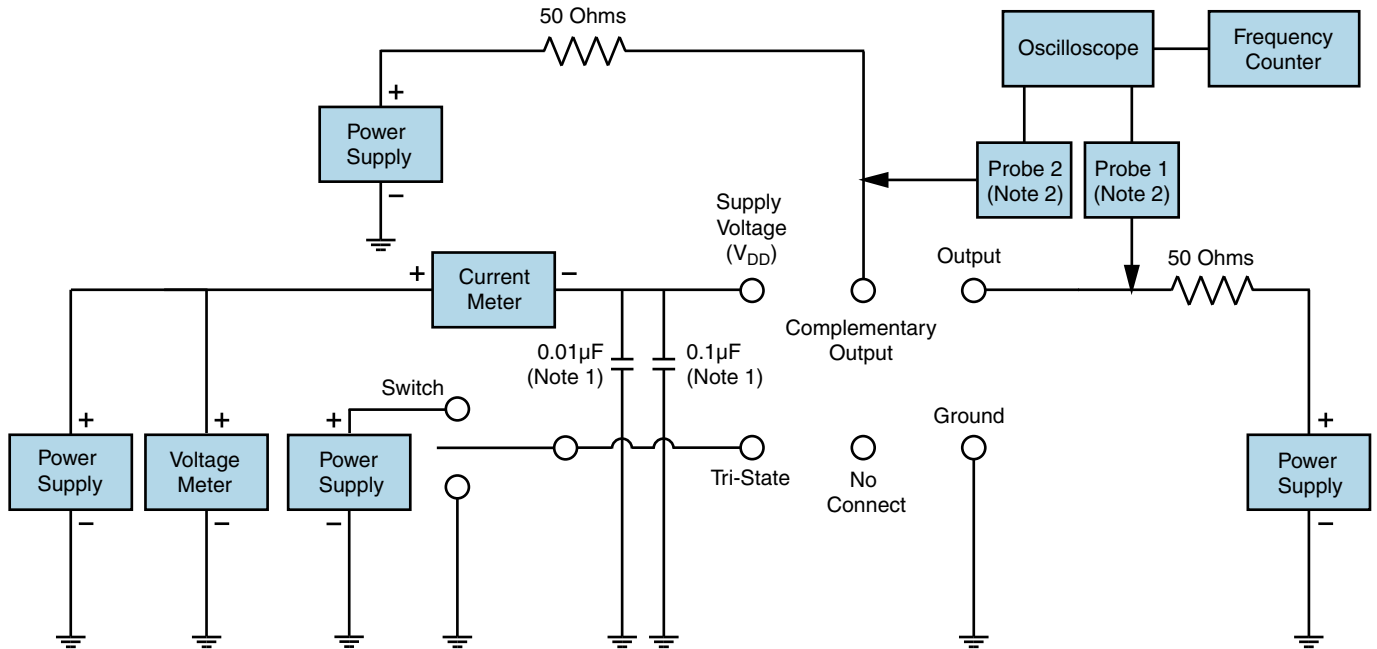


All Tolerances are ±0.1

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## OUTPUT WAVEFORM & TIMING DIAGRAM



**E15C7J2F-125.000M TR****Test Circuit for Tri-State and Complementary Output**

Note 1: An external  $0.01\mu\text{F}$  ceramic bypass capacitor in parallel with a  $0.1\mu\text{F}$  high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

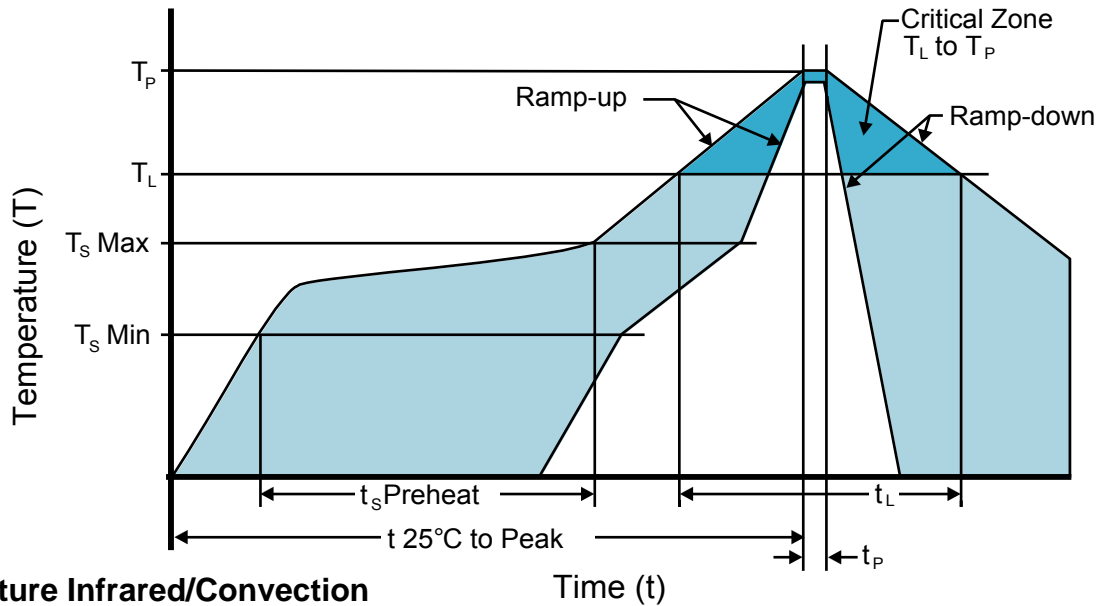
Note 2: A low capacitance ( $<12\text{pF}$ ), 10X attenuation factor, high impedance ( $>10\text{M}\Omega$ ), and high bandwidth ( $>500\text{MHz}$ ) passive probe is recommended.

Note 3: Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.



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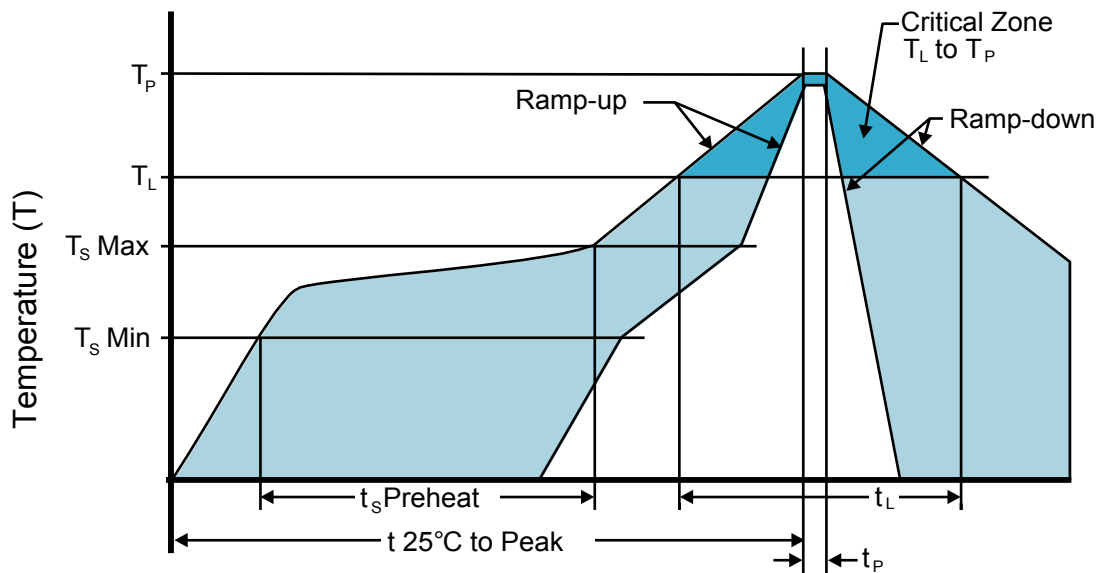
## Recommended Solder Reflow Methods

**High Temperature Infrared/Convection**

<b>T<sub>s</sub> MAX to T<sub>L</sub> (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (T <sub>s</sub> MIN)	150°C
- Temperature Typical (T <sub>s</sub> TYP)	175°C
- Temperature Maximum (T <sub>s</sub> MAX)	200°C
- Time (t <sub>s</sub> MIN)	60 - 180 Seconds
<b>Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (T <sub>L</sub> )	217°C
- Time (t <sub>L</sub> )	60 - 150 Seconds
<b>Peak Temperature (T<sub>P</sub>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (T<sub>P</sub> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (t<sub>p</sub>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

**$T_s$  MAX to  $T_L$  (Ramp-up Rate)** 5°C/Second Maximum

#### Preheat

- Temperature Minimum ( $T_s$  MIN) N/A
- Temperature Typical ( $T_s$  TYP) 150°C
- Temperature Maximum ( $T_s$  MAX) N/A
- Time ( $t_s$  MIN) 60 - 120 Seconds

**Ramp-up Rate ( $T_L$  to  $T_P$ )** 5°C/Second Maximum

#### Time Maintained Above:

- Temperature ( $T_L$ ) 150°C
- Time ( $t_L$ ) 200 Seconds Maximum

**Peak Temperature ( $T_P$ )** 240°C Maximum

**Target Peak Temperature ( $T_P$  Target)** 240°C Maximum 2 Times / 230°C Maximum 1 Time

**Time within 5°C of actual peak ( $t_p$ )** 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

**Ramp-down Rate** 5°C/Second Maximum

**Time 25°C to Peak Temperature (t)** N/A

**Moisture Sensitivity Level** Level 1

**Additional Notes** Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)